



1 Substrate: 1.59mm ±0.18mm [0.0625" ±0.007"]  
FR4/G10 or equivalent high temp material.

2 Pins: material- Brass Alloy 360 1/2 hard; finish-  
0.25µm [10µ"] Au over 1.27µm [50µ"] Ni (min.).

**Description:** Giga-snaP BGA SMT Land Socket

100 position BGA surface mount land pattern to terminal pins (1.0mm [0.039"] centers, 10x10 array)

**Tolerances:** diameters ±0.03mm [±0.001"], PCB perimeters ±0.13mm [±0.005"], PCB thicknesses ±0.18mm [±0.007"], pitches (from true position) ±0.08mm [±0.003"], all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

<b>LS-BGA100B-41 Drawing</b>	<b>Status:</b> Released	<b>Scale:</b> 6:1	<b>Rev:</b> C
 <p>© 2004 IRONWOOD ELECTRONICS, INC. PO BOX 21151 ST. PAUL, MN 55121 Tele: (651) 452-8100 www.ironwoodelectronics.com</p>	<b>Drawing:</b> H. Hansen		<b>Date:</b> 7/26/04
	<b>File:</b> LS-BGA100B-41 Dwg		<b>Modified:</b> 4/18/05